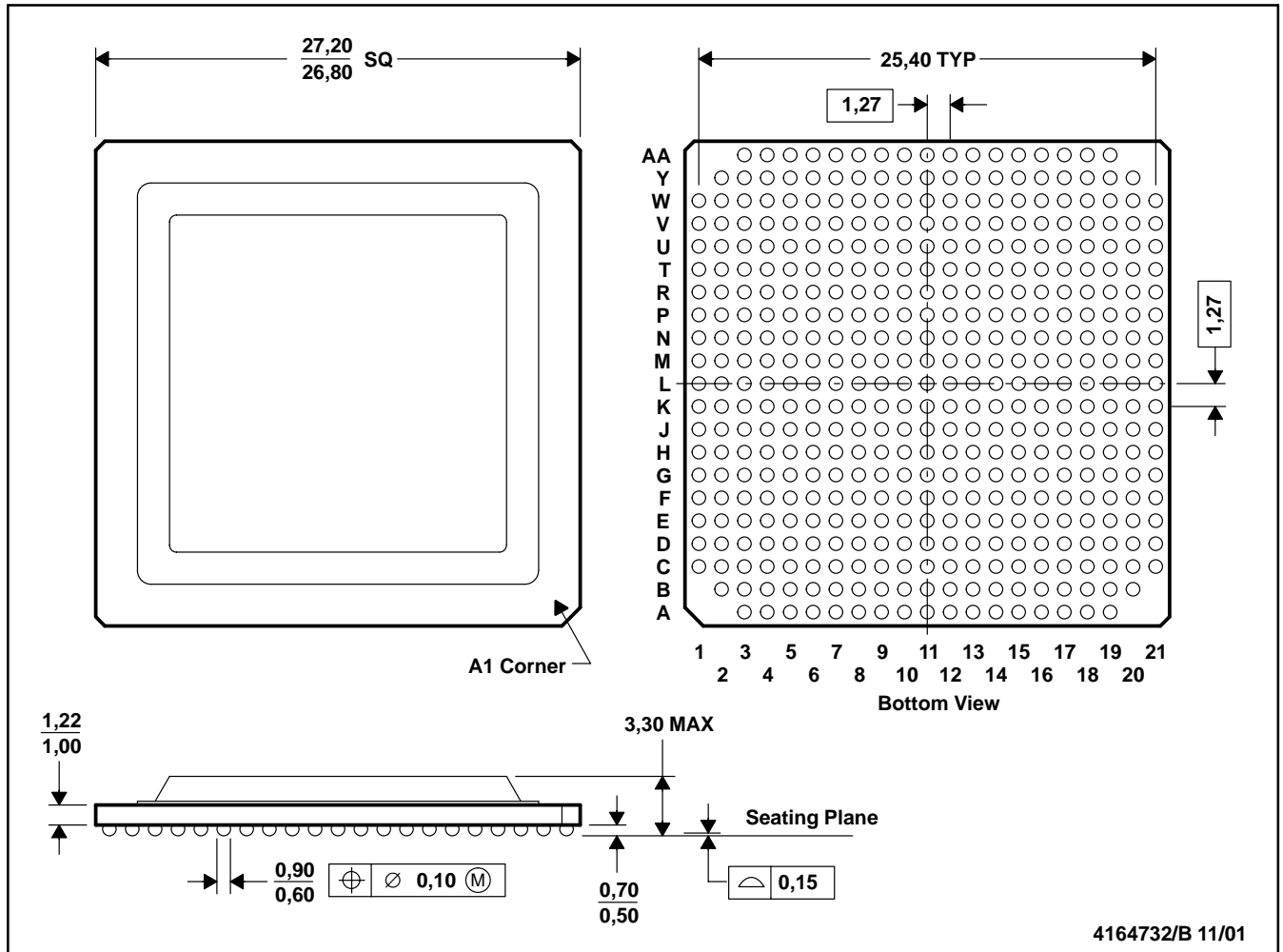


GLP (S-CBGA-N429)

CERAMIC BALL GRID ARRAY



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MO-156
 D. Flip chip application only

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